SHARP

GL480E00000F

Infrared Emitting Diode



Features

- 1. Side view emission type
- 2. Plastic mold with resin lens
- 3. Medium directivity angle ($\Delta \theta$: ±13° TYP.) Peak emission wavelength: 950 nm TYP.
- 4. Radiant flux φe: 0.7 mW MIN.
- 5. Lead free and RoHS directive component

Agency Approvals/Compliance

- 1. Compliant with RoHS directive (2002/95/EC)
- Content information about the six substances specified in "Management Methods for Control of Pollution Caused by Electronic Information Products Regulation" (popular name: China RoHS) (Chinese: 电子信息产品污染控制管理办法); refer to page 7

Applications

- 1. Office automation equipment
- 2. Audio visual equipment
- 3. Home appliances
- 4. Telecommunication equipment
- 5. Measuring equipment
- 6. Tooling machines
- 7. Computers

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Outline Dimensions



■ Absolute Maximum Ratings

Ta = 25°C						
Parameter	Symbol	Rating	Unit			
Forward current	۱ _F	50	mA			
Peak forward current *1	I _{FM}	1	А			
Reverse voltage	V _R	6	V			
Power dissipation	Р	75	mW			
Operating temperature	Topr	-25 to +85	°C			
Storage temperature	Tstg	-40 to +85	°C			
Soldering temperature *2	Tsol	260	°C			

*1 Pulse width: 100 µs, Duty ratio: 0.01

*2 5 s (MAX.) positioned 1.4 mm from the resin edge. See Figure 11.

Electro-optical Charactertistics

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Forward voltage	V _F	I _F = 20 mA	-	1.2	1.4	V
Peak forward voltage	V _{FM}	I _{FM} = 0.5 A		3.0	4.0	V
Reverse current	I _R	V _R = 3 V	-	-	10	μΑ
Radiant flux	$\Phi_{\!\!e}$	I _F = 20 mA	0.7	-	3.0	mW
Peak emission wavelength	λρ	I _F = 5 mA		950	-	nm
Half intensity wavelength	Δλ	I _F = 5 mA	_	45	-	nm
Terminal capacitance	Ct	V _R = 0, f = 1 MHz	-	50	-	pF
Response frequency	f _C		-	300	-	kHz
Angle of half intensity	$\Delta \theta$	I _F = 20 mA	_	±13	-	degrees



Fig. 1 Forward Current vs. **Ambient Temperature**

Fig. 2 Peak Forward Current vs. Duty Ratio



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Fig. 3 Spectral Distribution







Fig. 5 Forward Current vs. Forward Voltage



Fig. 6 Relative Radiant Flux vs. Ambient Temperature









Fig. 9 Relative Collector Current vs. Distance



Fig. 10 Radiation Diagram



Angular displacement $\boldsymbol{\theta}$

Design Considerations

Design Guidelines

- 1. Allow for natural degradation of the LED as a result of long continuous operation. This part will have 50% degradation in output after 5 years of continuous use.
- 2. This product is not designed to be electromagnetic- and ionized-particle-radiation resistant.

Manufacturing Guidelines

Cleaning Instructions

- 1. Confirm this device's resistance to process chemicals before use, as certain process chemicals may affect the optical characteristics.
- 2. Solvent cleaning: Solvent temperature should be 45°C or below. Immersion time should be 3 minutes or less.
- 3. Ultrasonic cleaning: The effect upon devices varies due to cleaning bath size, ultrasonic power output, cleaning time, PCB size and device mounting circumstances. Sharp recommends testing using actual production conditions to confirm the harmlessness of the ultrasonic cleaning methods.
- 4. Recommended solvent materials: Ethyl alcohol, Methyl alcohol, and Isopropyl alcohol.

Fig. 11 Soldering Area



Packing Specifications

- 1. Parts are packed in a vinyl bag, at an average quantity of 1,000 pieces per bag.
- 2. Bags are secured in a box as shown in illustration on page 8.
- 3. Product mass: 0.09 g (approx.)

■ Presence of ODCs (RoHS Compliance)

This product shall not contain the following materials, and they are not used in the production process for this product:

• Regulated substances: CFCs, Halon, Carbon tetrachloride, 1,1,1-Trichloroethane (Methylchloroform). Specific brominated flame retardants such as the PBBOs and PBBs are not used in this product at all.

This product shall not contain the following materials banned in the RoHS Directive (2002/95/EC).

- Lead, Mercury, Cadmium, Hexavalent chromium, Polybrominated biphenyls (PBB), Polybrominated diphenyl ethers (PBDE).
- Content information about the six substances specified in "Management Methods for Control of Pollution Caused by Electronic Information Products Regulation" (Chinese: 电子信息产品污染控制管理办法)

	Toxic and Hazdardous Substances					
Category	Lead (Pb)	mercury (Hg)	Cadmium (Cd)	Hexavalent chromiun (Cr ⁶⁺)	Polybrominated biphenyls (PBB)	Polybrominated diphenyl ethers (PBDE)
Infrared Emitting Diode	1	1	1	1	1	1

NOTE: \checkmark indicates that the content of the toxic and hazardous substance in all the homogeneous materials of the part is below the concentration limit requirement as described in SJ/T 11363-2006 standard.

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Package Specification



Sheet No.: D1-A01101EN

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(i) The devices in this publication are designed for use in general electronic equipment designs such as:

- --- Personal computers
- --- Office automation equipment
- --- Telecommunication equipment (terminal)
- --- Test and measurement equipment
- --- Industrial control
- --- Audio visual equipment
- --- Consumer electronics

(ii) Measures such as fail-safe function and redundant design should be taken to ensure reliability and safety when SHARP devices are used for or in connection with equipment that requires higher reliability such as:

- --- Transportation control and safety equipment (i.e., aircraft, trains, automobiles, etc.)
- --- Traffic signals
- --- Gas leakage sensor breakers
- --- Alarm equipment
- --- Various safety devices, etc.

(iii) SHARP devices shall not be used for or in connection with equipment that requires an extremely high level of reliability and safety such as:

- --- Space applications
- --- Telecommunication equipment (trunk lines)
- --- Nuclear power control equipment
- --- Medical and other life support equipment (e.g. scuba)

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